

SEA & LAND ELECTRONIC CORP.

WWW.SEALAND-PPTC.COM

ALPHA-TOP TECHNOLOGY CORP.

WWW.ALPHA-TOP.COM

APPROVAL SHEET

| MODEL NO.: | nSMD 035-33V | |
|------------------|--------------|--|
| | | |
| CUSTOMER: | | |
| | | |
| | | |
| CUSTOMER'S APPR | OVAL: | |
| AUTHORIZED SIGNA | ATURE/STAMP: | |
| | | |
| DATE | | |

MANUFACTURER:

HEAD OFFICE:

13F.,No.120-10,Sec.3,Zhongshan Rd.,Zhonghe Dist.,New Taipei City 23544,Taiwan

Tel: 886-2-8221-2567 Fax:882-2-2225-7268 E-mail:service@chipfast.com.tw

China Branch:

31 Chang-Xin-Zon Road,Gao-Ling Industrial Zone,Chiu-chang Town, Huey Yang Distric,Huey Zhou City,Guang Dong516221,CHINA

Tel: 86-752-3562001 Fax:86-752-3558696 E-mail:service@atpptc.com

Submitted by: Chung Cheng Approved by: YC Lin DATE: 18-Jan-21

SEA & LAND ELECTRONIC CORP.



nSMD 035-33V

Features

- Surface Mount Devices
- Lead free device
- Size 3.2*1.6 mm/0.12*0.06 inch
- Surface Mount packaging for automated assembly

Applications

Almost anywhere there is a low voltage power supply, up to 60V and a load to be

protected, including:

- Computer mother board, Modem. USB hub
- PDAs & Charger, Analog & digital line card
- Digital cameras, Disk drivers, CD-ROMs,

Alpha-Top (Sea&Land Alliance)

Performance Specification

| Madal | Mandalasa | V_{max} | I _{max} | I _{hold} | $I_{\rm trip}$ | P_d | | mum To Trip | Resis | tance | Agency . | Approval |
|-------------|-----------|------------------|------------------|-------------------|----------------|-------------|----------------|----------------|--------------------------|--------------|----------|----------|
| Model | Marking | (Vdc) | (A) | @25°C (A) | @25°C (A) | Max. (W) | Current (A) | Time (Sec) | Ri _{min} (Ω) | R1max (Ω) | UL | TUV |
| nSMD035-33V | αВ | 33.0 | 100 | 0.35 | 0.75 | 0.6 | 8.00 | 0.10 | 0.250 | 1.300 | | |

Ihold = Hold Current. Maximum current device will not trip in 25°C still air.

Itrip = Trip Current. Minimum current at which the device will always trip in 25°C still air.

Vmax = Maximum operating voltage device can withstand without damage at rated current (Imax).

Imax = Maximum fault current device can withstand without damage at rated voltage (Vmax).

= Power dissipation when device is in the tripped state in 25°C still air environment at rated voltage.

Rimin/max = Minimum/Maximum device resistance prior to tripping at 25°C.

R1_{max} = Maximum device resistance is measured one hour post reflow.

CAUTION: Operation beyond the specified ratings may result in damage and possible arcing and flame.

Environmental Specifications

| Test | Conditions | Resistance change | | | |
|--|----------------------------|-------------------|--|--|--|
| Passive aging | +85°C, 1000 hrs. | ±5% typical | | | |
| Humidity aging | +85°C, 85% R.H., 168 hours | ±5% typical | | | |
| Thermal shock | +85°C to -40°C, 20 times | ±33% typical | | | |
| Resistance to solvent | MIL-STD-202, Method 215 | No change | | | |
| Vibration | MIL-STD-202,Method 201 | No change | | | |
| Ambient operating conditions : | - 40 °C to 85 °C | | | | |
| Maximum surface temperature of the device in the tripped state is 125 °C | | | | | |

UL pending Agency Approvals :

Regulation/Standard: 2002/95/EC

EN14582

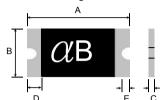
I. Versus Temperature

| •n | old voices iomporate | | | | | | | | | |
|-------|----------------------|-------|-------|-------------|---------------|-------------|-----------------------------|---------------|---------------------|------|
| Model | Model | | Max | kimum ambie | ent operating | temperature | e (T _{mao}) vs. h | old current (| I _{hold}) | |
| | Model | -40°C | -20°C | 0°C | 25°C | 40°C | 50°C | 60°C | 70°C | 85°C |
| Г | nSMD035-33V | 0.50 | 0.45 | 0.40 | 0.35 | 0.30 | 0.27 | 0.24 | 0.21 | 0.15 |

Construction And Dimension (Unit:mm)

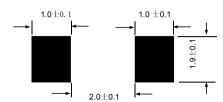
| Model | Model | | В | | | С | | E |
|-------------|-------|------|------|------|------|------|------|------|
| Wodel | Min. | Max. | Min. | Max. | Min. | Max. | Min. | Min. |
| nSMD035-33V | 3.00 | 3.50 | 1.50 | 1.80 | 0.50 | 1.20 | 0.15 | 0.10 |

Dimensions & Marking



α = Trademark B = Part identification

Recommended Pad Layout (mm)



Termination Pad Characteristics

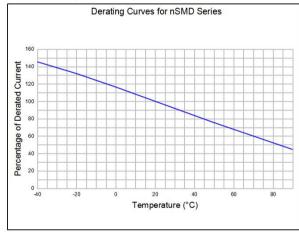
Tin-plated Nickel-Copper Terminal pad materials :

Meets EIA specification RS186-9E and ANSI/J-STD-002 Category 3. Terminal pad solderability :

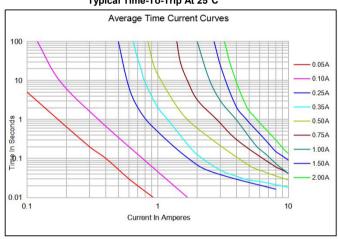
Rework

Use standard industry practices, the removal device must be replaced with a fresh one.

Thermal Derating Curve



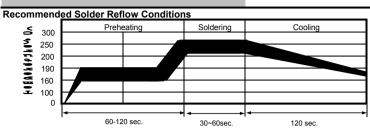
Typical Time-To-Trip At 25°C



- Use PPTC beyond the maximum ratings or improper use may result in device damage and possible electrical arcing and flame.
- PPTC are intended for protection against occasional over current or over temperature fault conditions and should not be used when repeated fault conditions or prolonged trip events are anticipated.

 Device performance can be impacted negatively if devices are handled in a manner inconsistent with recommended electronic, thermal, and mechanical procedures for electronic components.
- Use PPTC with a large inductance in circuit will generate a circuit voltage (L di/dt) above the rated voltage of the PPTC. Avoid impact PPTC device its thermal expansion like placed under pressure or installed in limited space.

- Contamination of the PPTC material with certain silicon based oils or some aggressive solvents can adversely impact the performance of the devices. PPTC SMD can be cleaned by standard methods. Requests that customers comply with our recommended solder pad layouts and recommended reflow profile. Improper board layouts or reflow profile could negatively impact solderability performance of our devices.

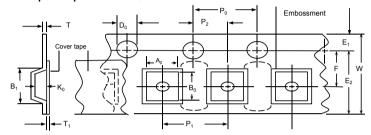


- Recommended reflow methods : IR, vapor phase oven, hot air oven.
- Devices are not designed to be wave soldered to the bottom side of the board.
- Recommended maximum paste thickness is 0.25 mm (0.010 inch).
- Devices can be cleaned using standard method and solvents.
- Note: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

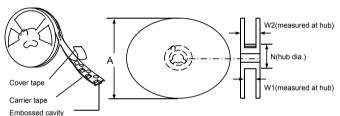
Tape And Reel Specifications (mm)

| 8.15 ± 0.3 4.0 ± 0.10 4.0 ± 0.10 2.0 ± 0.05 1.95 ± 0.10 3.45 ± 0.10 |
|---|
| 4.0 ± 0.10 2.0 ± 0.05 1.95 ± 0.10 |
| 2.0 ± 0.05 1.95 ± 0.10 |
| 1.95 ± 0.10 |
| |
| 2 45 ± 0 10 |
| 3.43 ± 0.10 |
| 4.35 |
| 1.5 + 0.1, -0 |
| 3.5 ± 0.05 |
| 1.75 ± 0.10 |
| 6.25 |
| 0.6 |
| 0.1 |
| 1.04 ± 0.1 |
| 390 |
| 160 |
| |
| 178 |
| 60 |
| 9 ± 0.5 |
| 12.6 ± 0.5 |
| |

EIA Tape Component Dimensions



EIA Reel Dimensions



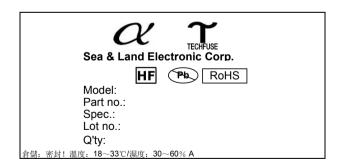
Storage And Handling

- Storage conditions: 40°C max, 70% R.H.
- Devices may not meet specified performance if storage conditions are exceeded.

| Order Information | | Packaging | | | |
|-------------------|----------------------------|-----------|----------------------|--|--|
| | nSMD | 035-33V | Tape & Reel Quantity | | |
| | Product name | Hold | | | |
| | Size 3216 mm / 1206 inch | Current | 3,500 pcs/reel | | |
| | SMD : surface mount device | 0.354 | | | |

Tape & reel packaging per EIA481-1

Labeling Information



X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Resettable Fuses - PPTC category:

Click to view products by TECHFUSE manufacturer:

Other Similar products are found below:

RF0077-000 RF3256-000 RF3281-000 RF3301-000 RF3344-000 RF3382-000 SMD125-2 RF2171-000 RF2531-000 RF2873-000 RF3060-000 TR600-150Q-B-0.5-0.130 RXE090 5E4795/04-1502 TRF250-080T-B-1.0-0.125 SMD100-2 NIS5452MT1TXG NIS5431MT1TXG SMD250-2 0ZCM0001FF2G 0ZCM0003FF2G 0ZCM0004FF2G BK60-017-DZ-E0.6 F95456-000 LVR100S RS30-090 RS30-600 RS30-700 RS30-800 RS30-900 RS60RB-010 RS60RB-020 RS60RB-025 RS60RB-050 RS60RB-075 RS60RB-160 ASMD0603-010-30V ASMD0603-025-16V ASMD2920-260-24V BSMD0603-025-12V BSMD1206-150-12V BSMD0805-020-33V BSMD1206-075-13.2V BSMD2920-400-6V BSMD2920-300-6V BSMD2920-700-6V SMD1812-750-12V SMD1206-300C-12V SB250-145